

Advance Product Change Notification

Issue Date: 23-Feb-2019

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201902020A



Management Summary

ON8077 & TFF1044 change of industrial flow from Amkor Taiwan and Amkor Philippines to Amkor Korea. Change Category

Change Calegory				
[]Wafer Fab Process	[] Assembly Process	[X] Product Marking	[] Test Location	[] Design
[] Wafer Fab Materials	[X] Assembly Materials	[] Mechanical Specification	[]Test Process	[]Errata
[] Wafer Fab Location	[X] Assembly Location	[] Packing/Shipping/Labeling	[] Test g Equipment	[] Electrical spec./Test coverage
] Firmware	[] Other			
ON8077 & TFF1044:				
Bumping/Assembly Transfer				
from Amkor				
Taiwan/Philippines to Amkor				
Korea.				

Description of Change

Change of industrial flow from Amkor Taiwan and Amkor Philippines to Amkor Korea. In the current flow wafer bumping is done by ATT5 (Taiwan) and assembly is done by ATP3 (Philippines), in the new flow both bumping and assembly will be done by ATK4 (Korea).

To be aligned with Amkor Korea assembly process, during this transfer a standard released ATK4 molding compound will be qualified for the product as this compound is a new material for these products. The current ATP3 compound is Hitachi GE100RFC32, the new ATK4 compound is Sumitomo G355. **Reason for Change**

Discontinuation of FC-CSP assembly at ATP3 and simplify supply chain to have both (bumping/assembly) in one location. **Identification of Affected Products** Top side marking

Product Availability

Sample Information

Samples are available from 15-Mar-2019

Production Planned first shipment 21-Jun-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 22-Mar-2019. The Final PCN is planned to be issued on: 22-Mar-2019.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 25-Mar-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Changed Orderable Part#

TFF1044HN/N1Y

Changed Part 12NC 935304432518 New Orderable Part# TFF1044HN/N1/AY

New part 12NC 935378072518